

Features

- Frequency range : 24MHz to 80MHz
- Extremely small SMD type crystal
- 4 pad AuSn sealing, ceramic package
- High precision and frequency stability
- External dimensions (mm)
L : 1.2 x W : 1.0 x H : 0.33
- RoHS and REACH compliant & Pb free

Applications

- Wearable devices
- Wi-Fi, BT or other wireless module
- IoT devices
- Smart phone
- Space limited application

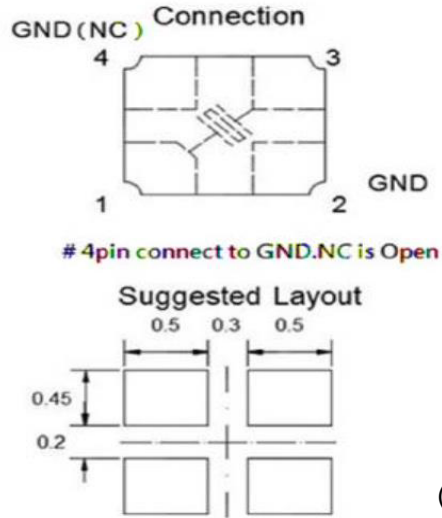
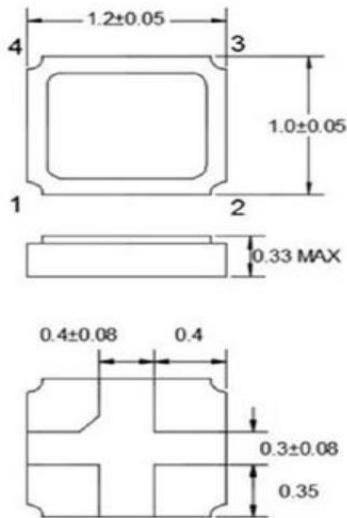
Electrical Characteristics

Item		8J	Conditions
Frequency Range	F_0	24MHz ~ 80MHz	
Frequency Tolerance	F_{tol}	$\pm 30\text{ppm}$, $\pm 20\text{ppm}$, $\pm 10\text{ppm}$	at 25°C
Frequency Stability over Operating Temperature Range (refer to 25°C)	F_{stab}	$\pm 30\text{ ppm}$	-20°C ~ +70°C
		$\pm 20\text{ ppm}$	
		$\pm 10\text{ ppm}$	
		$\pm 10\text{ ppm}$	-30°C ~ +85°C
		$\pm 30\text{ ppm}$	-40°C ~ +85°C
		$\pm 20\text{ ppm}$	
Operating Temperature Range	T_{OTR}	-20°C ~ +70°C	
		-40°C ~ +85°C	
Shunt Capacitance	C_0	3pF Max.	
Drive Level	D_L	1 ~ 200μW (100μW Typ.)	
Load Capacitance	C_L	6pF, 8pF, 10pF, 12pF	
Aging	F_{aging}	$\pm 3\text{ ppm Max.}$	at 25°C $\pm 3^\circ\text{C}$, first year
Storage Temperature Range	T_{STR}	-55°C ~ +125°C	

Motional Resistance (ESR)

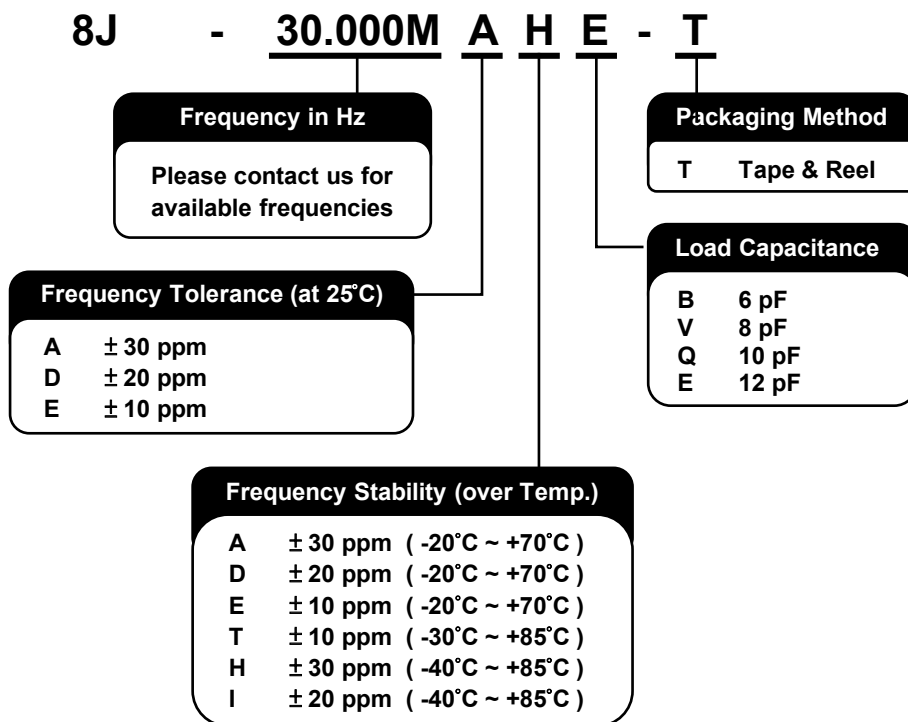
Fundamental	
24 ~ 32 MHz	100Ω Max.
37.4 ~ 48 MHz	80Ω Max.
> 48 MHz	60Ω Max.

Dimensions

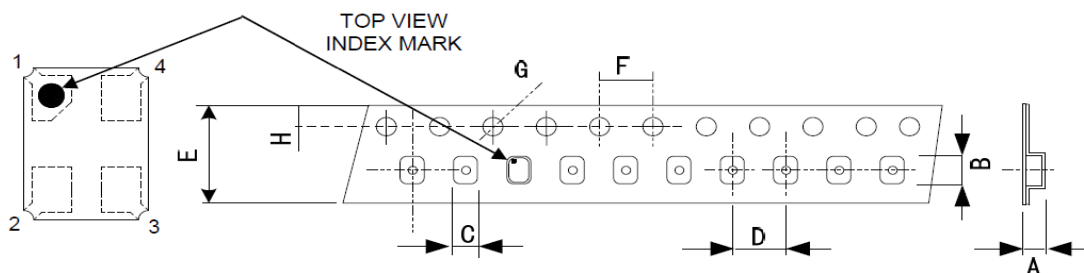


(Unit: mm)

Ordering Information

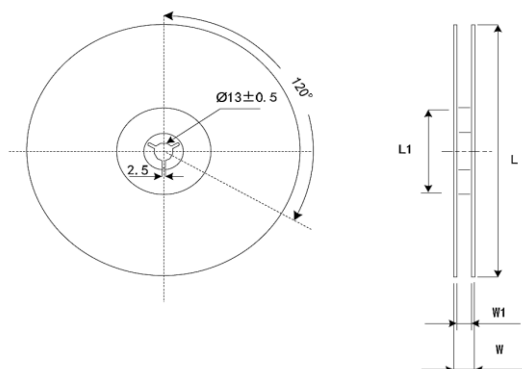


Packing



DIMENSIONS	A	B	C	D	E	F	G	H
	0.45 ±0.05	1.30 ±0.05	1.10 ±0.05	4.00 ±0.10	8.00 ±0.20	4.00 ±0.10	1.55 ±0.05	1.75 ±0.10

(Unit: mm)



DIMENSIONS	L	L1	W	W1
	178 ±1.00	60.2 ±0.50	11.5 ±0.2	8 +1/-0

(Unit: mm)

Reflow Profile

Solder melting point : 220°C ± 10°C, 60 sec. Min.

Peak temperature : 260°C ± 10°C, 10 sec. Min.

